

# MSP-EXP430G2 LaunchPad Evaluation Kit

## User's Guide



Literature Number: SLAU318E  
July 2010–Revised March 2014

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# **MSP-EXP430G2 LaunchPad Evaluation Kit**

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## **Preface: Read This First**

### **If You Need Assistance**

If you have any feedback or questions, support for the MSP430™ devices and the MSP-EXP430G2 is provided by the Texas Instruments Product Information Center (PIC) and the TI E2E Forum (<http://e2e.ti.com/>). Contact information for the PIC can be found on the TI web site at <http://support.ti.com>. Additional device-specific information can be found on the MSP430 web site at <http://www.ti.com/msp430>.

### **Related Documentation from Texas Instruments**

The primary sources of MSP430 information are the device-specific data sheets and user's guides available at the Texas Instruments MSP430 web site: <http://www.ti.com/msp430>.

MSP430 device user's guides, application reports, software examples and other MSP430 user's guides can be found at the Tech Docs section. The CCS user's guide includes detailed information on setting up a project and using Code Composer Studio™ for the MSP430 microcontroller ([SLAU157](http://www.ti.com/lit/zip/SLAU157)).

Information specific to the MSP-EXP430G2 LaunchPad Evaluation Kit, all the available IDEs, Software Libraries, and examples can be found at the Tools & Software section: <http://www.ti.com/tool/msp-exp430g2>.

## **1 MSP-EXP430G2 LaunchPad Overview**

### **1.1 Overview**

The MSP-EXP430G2 LaunchPad is an inexpensive and simple evaluation kit for the MSP430G2xx Value Line series of microcontrollers. It is an easy way to start developing on the MSP430 with on-board emulation for programming and debugging as well as buttons and LEDs for a simple user interface.

Rapid prototyping is simplified by the 20-pin BoosterPack headers which support a wide range of available BoosterPack plug-in modules. You can quickly add features like wireless connectivity, graphical displays, environmental sensing, and much more. You can either design your own BoosterPack or choose among many already available from TI and third party developers.

The LaunchPad features an integrated DIP target socket that supports up to 20 pins, allowing MSP430™ Value Line devices to be plugged into the LaunchPad board. The MSP-EXP430G2 LaunchPad comes with an MSP430G2553 device by default. The MSP430G2553 has the most memory available of the compatible Value Line devices.

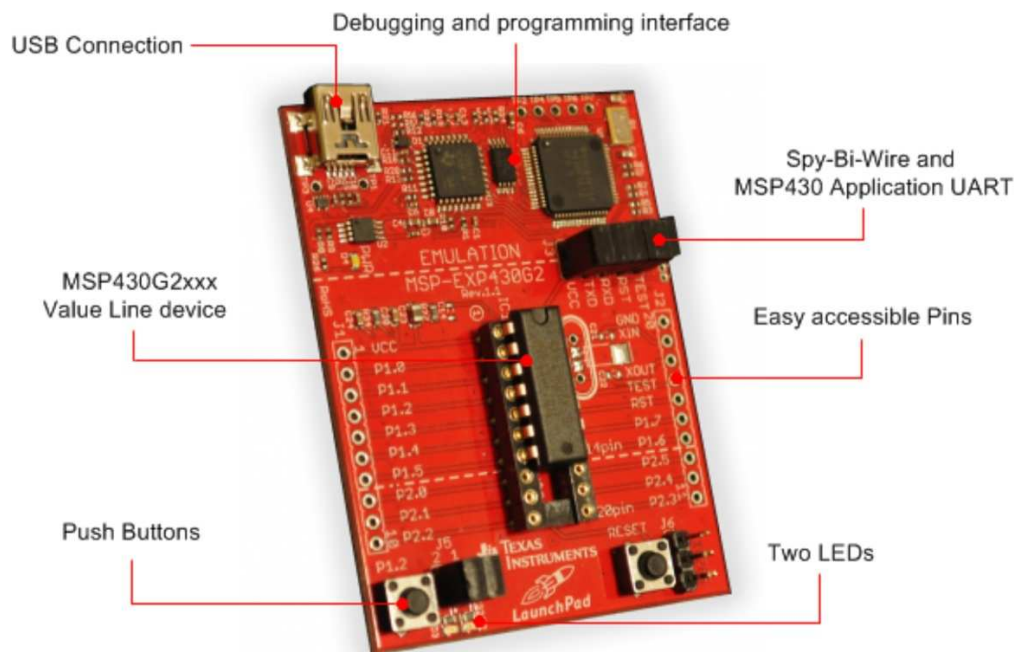
The MSP430G2553 16-bit MCU has 16KB flash, 512 bytes RAM, up to 16-MHz CPU speed, 10-bit ADC, capacitive touch enabled I/Os, universal serial communication interface, and more – plenty to get you started in your development.

Free software development tools are also available: TI's Eclipse-based Code Composer Studio™ IDE (CCS), IAR Embedded Workbench™ IDE (IAR), and the community-driven Energia open source code editor. More information about the LaunchPad, including documentation and design files, can be found on the tool page at <http://www.ti.com/tool/msp-exp430g2>.

## 1.2 Features

MSP-EXP430G2 LaunchPad features:

- USB debugging and programming interface featuring a driverless installation and application UART serial communication with up to 9600 Baud
- Supports MSP430G2xx2, MSP430G2xx3, and MSP430F20xx devices in PDIP14 or PDIP20 packages (see [Section 4.7](#) for a complete list of supported devices)
- Two general-purpose digital I/O pins connected to green and red LEDs for visual feedback
- Two push button for user feedback and device reset
- Easily accessible device pins for debugging purposes or as socket for adding customized extension boards
- High-quality 20-pin DIP socket for an easy plug-in or removal of the target device



**Figure 1. MSP-EXP430G2 LaunchPad Overview**

## 1.3 Kit Contents

The MSP-EXP430G2 evaluation kit includes the following hardware:

- LaunchPad emulator socket board (MSP-EXP430G2)
- Mini USB-B cable, 0.5 m
- Two MSP430 flash devices
  - MSP430G2553: Low-power 16-bit MSP430 microcontroller with an 8-channel 10-bit ADC, on-chip comparator, touch-sense enabled I/Os, universal serial communication interface, 16kB flash memory, and 512 bytes of RAM (preloaded with a sample program)
  - MSP430G2452: Low-power 16-bit MSP430 microcontroller with an 8-channel 10-bit ADC, on-chip comparator, touch-sense enabled I/Os, universal serial interface, 8kB flash memory, and 256 bytes of SRAM
- Two 10-pin PCB connectors female
- 32.768-kHz clock crystal from Micro Crystal (<http://www.microcrystal.com>)
- Quick start guide
- Two LaunchPad stickers

## 1.4 Revisions

The first production revision of the LaunchPad in 2010 was 1.3. In 2012 the LaunchPad board revision changed from 1.4 to 1.5 to align with the new release of Value Line devices. The differences in the schematic and the kit contents are:

- Layout and Schematic:
  - Voltage feedback in the emulator changed to increase startup stability (Rev 1.3 to Rev 1.4)
  - Rearranged jumper J3 to support two UART configurations: vertical (SW UART), horizontal (HW UART)
  - VCC on the connector J4 can now be disconnected from the emulator VCC by J3
  - Pullup resistor R34 and capacitor C24 on P1.3 removed to reduce the current consumption
  - Presoldered male headers J1 and J2

## 2 Installation

The MSP-EXP430G2 LaunchPad installation consists of three easy steps:

1. Download the required software.
2. Install the selected IDE.
3. Connect the LaunchPad to the PC.

Then the LaunchPad is ready to develop applications or to use the pre-programmed demo application.

### 2.1 Download the Required Software

Different development software tools are available for the MSP-EXP430G2 LaunchPad development board. IAR Embedded Workbench™ KickStart IDE and Code Composer Studio™ (CCS) IDE are both available in a free limited version. IAR Embedded Workbench allows 4KB of C-code compilation. CCS is limited to a code size of 16KB. The software is available at <http://www.ti.com/mspds>. There are many other compilers and integrated development environments (IDEs) available to use with the MSP-EXP430 LaunchPad including Rowley Crossworks and MSPGCC. However, example projects have been created using IAR Embedded Workbench KickStart IDE and Code Composer Studio IDE (CCS). For more information on the supported software and the latest code examples, visit the LaunchPad tool page (<http://www.ti.com/tool/msp-exp430g2>).

### 2.2 Install the Software

Download one of the integrated development environments (IDEs) (see [Section 2.1](#)). IAR KickStart and CCS offer the required driver support to work with the MSP-EXP430 LaunchPad onboard emulation. Once installed, the IDE should find the MSP-EXP430G2 LaunchPad as USB:HID debugging interface. Now all is set for developing MSP430G2xx based application on the LaunchPad.

### 2.3 Install the Hardware

Connect the MSP-EXP430G2 LaunchPad socket board with the enclosed USB cable to a PC. The driver installation starts automatically. If prompted for software, allow Windows to install the software automatically. This is possible only if either IAR KickStart or CCS is already installed.

## 3 Getting Started With MSP-EXP430G2 LaunchPad

### 3.1 Getting Started

The first time the MSP-EXP430G2 LaunchPad Evaluation Kit is used, a demo application automatically starts as soon as the board is powered from the USB host. To start the demo, connect the MSP-EXP430G2 LaunchPad with the included mini USB cable to a free USB port. The demo application starts with an LED toggle to show the device is active. More information about the demo application can be found in [Section 3.2](#).

### 3.2 Demo Application, Internal Temperature Measurement

The LaunchPad includes a pre-programmed MSP430G2553 device already installed in the target socket. When LaunchPad is connected via USB, the demo starts with an LED toggle sequence. The onboard emulation generates the supply voltage and all the signals necessary to start.

Press button P1.3 to switch the application to a temperature measurement mode. A reference temperature is taken at the beginning of this mode, and the LEDs of the LaunchPad signal a rise or fall in temperature by varying the brightness of the on-board red or green LED, respectively. The reference temperature can also be recalibrated with another button press on P1.3. The collected temperature data is also communicated via back-channel UART through the USB emulation circuitry back to the PC. The internal temperature sensor data from the MSP430G2553 device is sent to the PC to be displayed on the GUI. The pre-loaded demo application and the GUI are found in the Software Examples zip folder. The GUI is opened with LaunchPad\_Temp\_GUI.exe. This GUI is made with Processing (<http://processing.org>) with the source available for customization. The serial communication port on the PC must be configured with 2400 bps, one stop bit, and no flow control to display the values correctly.

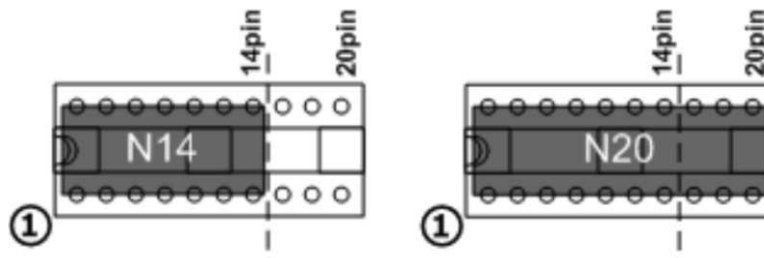
The demo application uses the on-chip peripherals of the MSP430G2553 device such as the 10-bit ADC, which samples the internal temperature sensor, and 16-bit timers, which drive the PWM to vary brightness of the LEDs and enable software UART for communication with the PC. The MSP430G2553 offers a USCI interface that is capable of communicating through UART at up to 2 MBaud, but to be aligned with all the other MSP430G2xx devices, the demo uses the Timer UART implementation, which can be used on all the other devices. This way the demo can be used with any other MSP430G2xx device with an integrated ADC, without any change in the program.

The provided applications can be a great starting point for various custom applications and give a good overview of the various applications of the MSP430G2xx Value Line devices.

## 4 Develop an Application With the MSP-EXP430G2 LaunchPad

### 4.1 Developing an Application

The integrated development environments (IDEs) shown in [Section 2](#) offer support for the whole MSP430G2xx Value Line. The MSP-EXP430G2 LaunchPad needs only a connection to the USB of the Host PC—there is no external hardware required. The power supply and the Spy-Bi-Wire JTAG signals TEST and RST must be connected with jumper J3 to allow the onboard emulation connection to the device. Now the preferred device can be plugged into the DIP target socket of the LaunchPad (see [Figure 2](#)). Both PDIP14 and PDIP20 devices of the MSP430G2xx Value Line and the MSP430F20xx family can be inserted into the DIP socket aligned to pin 1. A complete list of supported devices can be found in [Section 4.7](#).



**Figure 2. Insert Device Into Target Socket**

The following example for Code Composer Studio shows how to download and debug the demo application described in [Section 3.2](#).

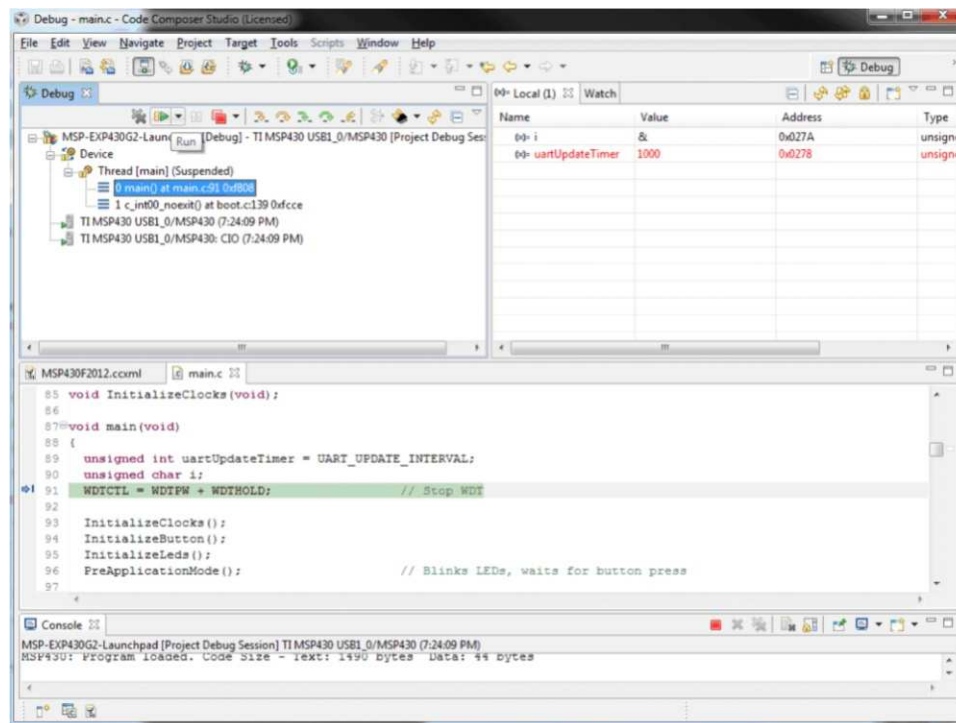
### 4.2 Program and Debug the Temperature Measurement Demo Application

The source code of the demo application can be found in the [Software Examples](#) zip folder. Download the project folder and unpack it to a location of your choice. For this demo, Code Composer Studio v4 or newer must be installed.

The demo application can be loaded to the CCS workspace by clicking File→Import. Select the location of the extracted project files and import Existing projects into Workspace. Now the MSP-EXP430G2-Launchpad project appears inside the CCS workspace. The project must be marked as the active project to start programming and debugging the device.

Connect the LaunchPad with an inserted MSP430G2553 device to the host PC and click the Debug button on the CCS Toolbar. The MSP-EXP430G2 LaunchPad is initialized and the download of the compiled demo application starts. The CCS view switches to a debugging interface once the download is completed and the application is ready to start. [Figure 3](#) shows Code Composer Studio v4 with the MSP-EXP430G2 LaunchPad demo application in debug view.





**Figure 3. Code Composer Studio™ v4 in Debugging Mode**

### 4.3 Disconnect Emulator From Target With Jumper J3

The connection between the MSP-EXP430G2 emulator and the attached target device can be opened with the jumper array J3. This can be useful to access an attached eZ430 target board by disconnecting the Spi-Bi-Wire JTAG lines RST and TEST or if the JTAG lines are used for other application purposes. The jumper array can also be used to measure the power consumption of the LaunchPad application. For this intention, all connections except VCC must be opened, and a multi meter can be used on the VCC Jumper to measure the current of the MSP-EXP430G2 target device and its peripherals. The jumper J5 VCC also must be opened if the LaunchPad board is powered with an external power supply over J6 [Table 1](#) or the eZ430 interface J4.

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**NOTE:** The assignment of jumper J3 has been changed in MSP-EXP430G2 revision 1.5, see the comments in [Table 1](#) to find the assignment for a specific board revision.

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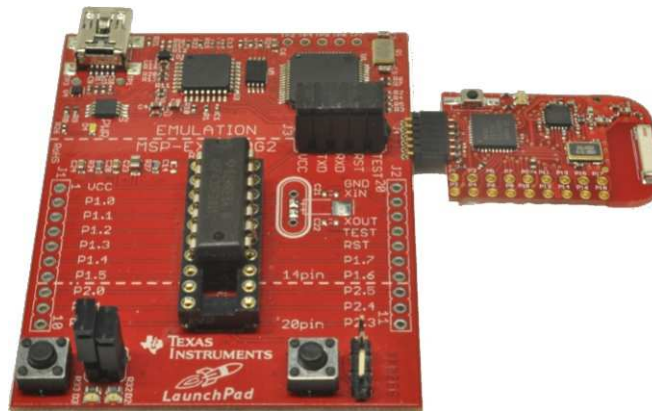
**Table 1. Jumper Connection J3 Between Emulator and Target**

Jumper	Signal	Description
1	VCC	Target socket power supply voltage (power consumption test jumper) (located on 5 before Rev. 1.5)
2	TEST	Test mode for JTAG pins or Spy-Bi-Wire test clock input during programming and test (located on 1 before Rev. 1.5)
3	RST	Reset or Spy-Bi-Wire test data input/output during programming and test (located on 2 before Rev. 1.5)
4	RXD	UART receive data input (direction can be selected by jumper orientation) (located on 3 before Rev. 1.5)
5	TXD	UART transmit data output (direction can be selected by jumper orientation) (located on 4 before Rev. 1.5)

Jumpers 4 and 5 connect the UART interface of the emulator to the target device pins P1.1 and P1.2. The direction of the UART signal lines can be selected by the orientation of the attached jumpers. In horizontal orientation, the jumpers connect TXD to P1.1 and RXD to P1.2, as they are used for the software UART communication on the demo application (see [Section 3.2](#)). In vertical orientation, the jumpers connect the TXD signal to P1.2 and the RXD signal to P1.1, as required for the MSP430G2553 USCI.

#### 4.4 Program Connected eZ430 Target Boards

The MSP-EXP430G2 LaunchPad can program the eZ430-RF2500T target boards, the eZ430-Chronos watch module, or the eZ430-F2012T/F2013T. To connect one of the eZ430 targets, connector J4 must be populated with a 0.050-in (1.27-mm) pitch male header, as shown in [Figure 4](#).



**Figure 4. MSP-EXP430G2 LaunchPad With Attached eZ430-RF2500 Target Board**

To program the attached target without interfering with the LaunchPad socket board, jumper connections TEST and RST of J3 must be open. The interface to the eZ430 target board is always connected to the MSP-EXP430G2 emulator, so the programming and debugging of a connected LaunchPad target device is possible only if the eZ430 target is not connected on the same time. The application UART, on the other hand, is connected directly to the LaunchPad target device, and jumper J3 can be closed to monitor the transmission from the LaunchPad target to the attached eZ430. This way both possible connections, from the device to the PC and from the device to the eZ430, can be established without changing the direction of the UART pins.

The VCC connection to the eZ430 interface is directly connected to the LaunchPad target VCC and can be separated with jumper J3, if the LaunchPad itself should be powered via a connected battery on J4. To supply the eZ430 interface with the onboard emulator the jumper J3 VCC needs to be closed.

[Table 2](#) shows the pinout of the eZ430 debugging interface J4, the first pin is the left pin located on the emulator part of the LaunchPad.

**Table 2. eZ430 Debugging Interface**

Pin	Signal	Description
1	TXD	UART transmit data output (UART communication from PC or MSP430G2xx to eZ430 target board)
2	VCC	Power supply voltage (J3 VCC needs to be closed to supply via onboard emulator)
3	TEST / SBWTCK	Test mode for JTAG pins and Spy-Bi-Wire test clock input during programming and test
4	$\overline{\text{RST}}$ / SBWTDIO	Reset, Spy-Bi-Wire test data input/output during programming and test
5	GND	Power supply ground
6	RXD	UART receive data input (UART communication from eZ430 target board to PC or MSP430G2xx)

#### 4.5 Connecting a Crystal Oscillator

The MSP-EXP430G2 LaunchPad offers a footprint for a variety of crystal oscillators. The XIN and XOUT signals of the LFXT1 oscillator can support low-frequency oscillators like a watch crystals of 32768 Hz or a standard crystal with a range defined in the associated data sheet. The signal lines XIN and XOUT can also be used as multipurpose I/Os or as a digital frequency input. More information on the possibilities of the low-frequency oscillator and the possible crystal selection can be found in the *MSP430x2xx Family User's Guide* ([SLAU144](#)) or the device-specific data sheet.

The oscillator signals are connected to J2 to use the signals on an attached application board. In case of signal distortion of the oscillator signals that leads to a fault indication at the basic clock module, resistors R29 and R28 can be used to disconnect the pin header J2 from the oscillating lines.

## 4.6 Connecting a BoosterPack

The LaunchPad can connect to many BoosterPacks within the ecosystem. The BoosterPack headers J1 and J2 along with power supply J6 fall on a 100-mil (0.1-in) grid to allow for easy and inexpensive development with a breadboard. The LaunchPad adheres to the 20-pin LaunchPad pinout standard. A standard was created to aid compatibility between LaunchPads and BoosterPacks, across the TI ecosystem.

The 20-pin standard is backward compatible with the 40-pin standard used by LaunchPads like the [MSP-EXP430F5529LP](http://www.ti.com/launchpad). This allows a subset of some 40-pin BoosterPacks to be used with 20-pin LaunchPads.

While most BoosterPacks are compliant with the standard, some are not. The LaunchPad is compatible with all 20-pin (and 40-pin) BoosterPacks that are compliant with the standard. If the reseller or owner of the BoosterPack does not explicitly indicate compatibility with the MSP430G2 LaunchPad, you might want to compare the schematic of the candidate BoosterPack with the LaunchPad, to ensure compatibility. Keep in mind that sometimes conflicts can be resolved by changing the G2 device pin function configuration in software. More information about compatibility can also be found at <http://www.ti.com/launchpad>.

## 4.7 Supported Devices

Texas Instruments offers several MSP430 devices in a PDIP package that is compatible with LaunchPad. [Table 3](#) shows the supported devices.

**Table 3. Supported Devices**

Part Number	Family	Description
<a href="#">MSP430F2001</a>	F2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 128B RAM, Comparator
<a href="#">MSP430F2002</a>	F2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 128B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430F2003</a>	F2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 128B RAM, 16-Bit Sigma-Delta A/D, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430F2011</a>	F2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 128B RAM, Comparator
<a href="#">MSP430F2012</a>	F2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 128B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430F2013</a>	F2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 128B RAM, 16-Bit Sigma-Delta A/D, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430G2001</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 512B Flash, 128B RAM
<a href="#">MSP430G2101</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 128B RAM
<a href="#">MSP430G2111</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 128B RAM, Comparator
<a href="#">MSP430G2121</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 128B RAM, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430G2131</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 128B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430G2201</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 128B RAM
<a href="#">MSP430G2211</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 128B RAM, Comparator
<a href="#">MSP430G2221</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 128B RAM, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430G2231</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 128B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C
<a href="#">MSP430G2102</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 256B RAM, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2202</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2302</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 4KB Flash, 256B RAM, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2402</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 256B RAM, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2112</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 256B RAM, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2212</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2312</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 4KB Flash, 256B RAM, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2412</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 256B RAM, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins

**Table 3. Supported Devices (continued)**

Part Number	Family	Description
<a href="#">MSP430G2132</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 256B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2232</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2332</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 4KB Flash, 256B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2432</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 256B RAM, 10-Bit SAR A/D, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2152</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 256B RAM, 10-Bit SAR A/D, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2252</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, 10-Bit SAR A/D, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2352</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 4KB Flash, 256B RAM, 10-Bit SAR A/D, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2452</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 256B RAM, 10-Bit SAR A/D, Comparator, USI for SPI/I <sup>2</sup> C, 16 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2153</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 1KB Flash, 256B RAM, 10-Bit SAR A/D, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2203</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2313</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2333</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, 10-Bit SAR A/D, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2353</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 2KB Flash, 256B RAM, 10-Bit SAR A/D, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2403</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 512B RAM, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2413</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 512B RAM, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2433</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 512B RAM, 10-Bit SAR A/D, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2453</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 8KB Flash, 512B RAM, 10-Bit SAR A/D, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2513</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 16KB Flash, 512B RAM, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2533</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 16KB Flash, 512B RAM, 10-Bit SAR A/D, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins
<a href="#">MSP430G2553</a>	G2xx	16-bit Ultra-Low-Power Microcontroller, 16KB Flash, 512B RAM, 10-Bit SAR A/D, Comparator, USCI for I <sup>2</sup> C/SPI/UART, 24 Capacitive-Touch Enabled I/O Pins

## 4.8 MSP-EXP430G2 On-Board Emulator

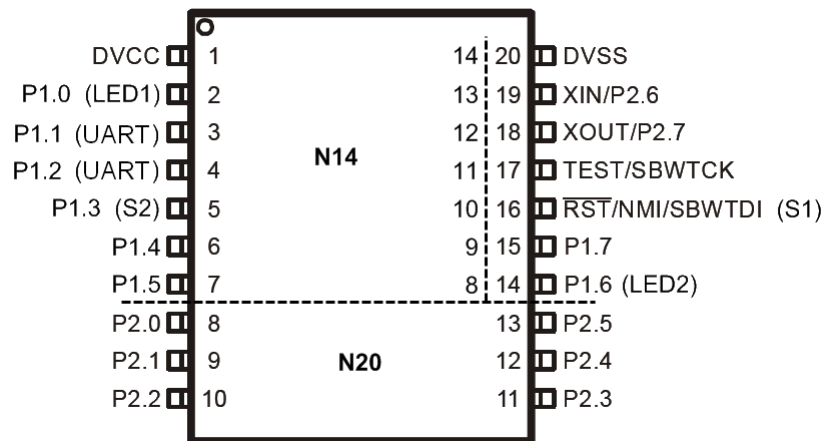
The MSP-EXP430G2 on-board emulator enables programming and debugging of supported MSP430 devices (see [Section 4.7](#)). It offers several features that are enabled by a 2-wire JTAG interface called Spy-Bi-Wire. For a more feature-complete emulator, the [MSP-FET430UIF](#) flash emulation tool may be more appropriate. See [Table 4](#) for more details on the MSP-EXP430G2 LaunchPad on-board emulator.

**Table 4. Features Supported by On-Board Emulator**

Feature	Support by LaunchPad (MSP-EXP430G2)
Supports MSP430F20xx, F21x2, F22xx, G2x01, G2x11, G2x21, G2x31, G2x53	✓
Allows fuse blow	
Adjustable target supply voltage	
Fixed 2.8-V target supply voltage	
Fixed 3.6-V target supply voltage	✓
4-wire JTAG	
2-wire JTAG	✓
Application UART	✓
Supported by CCS	✓
Supported by IAR	✓

## 5 MSP-EXP430G2 Hardware

### 5.1 Device Pinout



**Figure 5. Device Pinout**



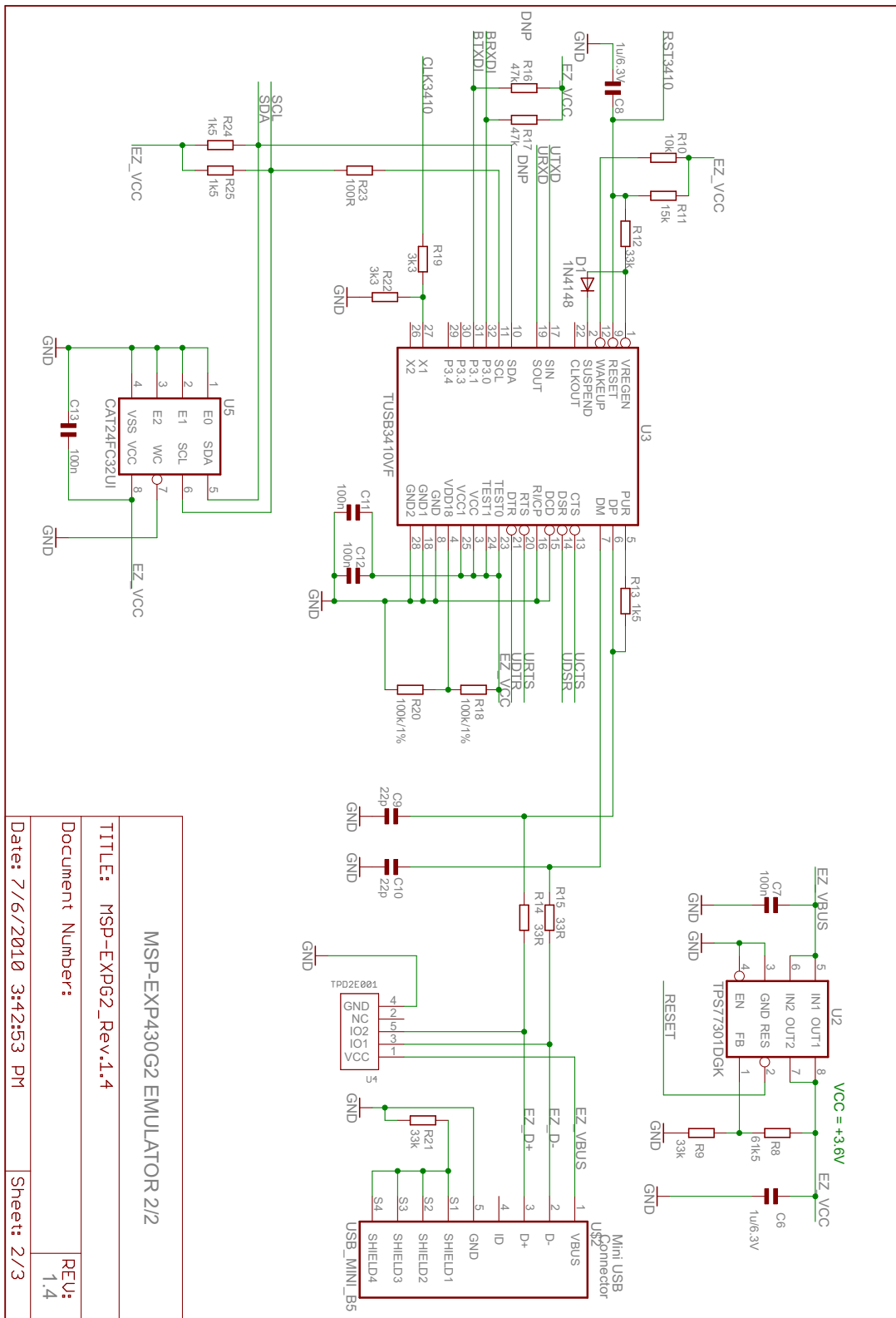


Figure 7. Schematics, MSP-EXP430G2 Emulator (2 of 2), Revision 1.4

MSP-EXP430G2 EMULATOR 2/2	
TITLE: MSP-EXP430G2_Rev.1.4	
Document Number:	
Date: 7/6/2010 3:42:53 PM	Sheet: 2/3
REV: 1.4	

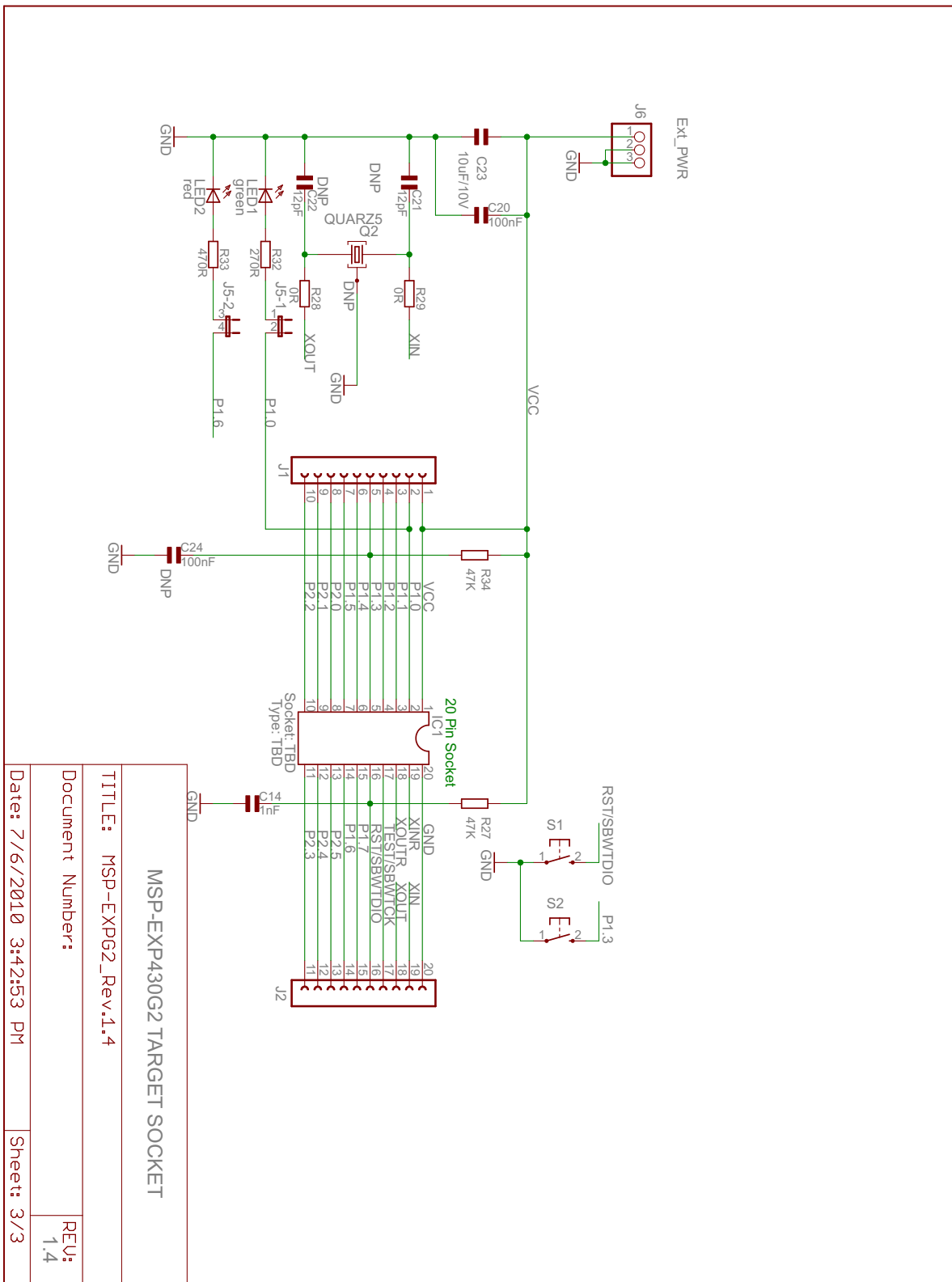


Figure 8. Schematics, MSP-EXP430G2 Target Socket, Revision 1.4



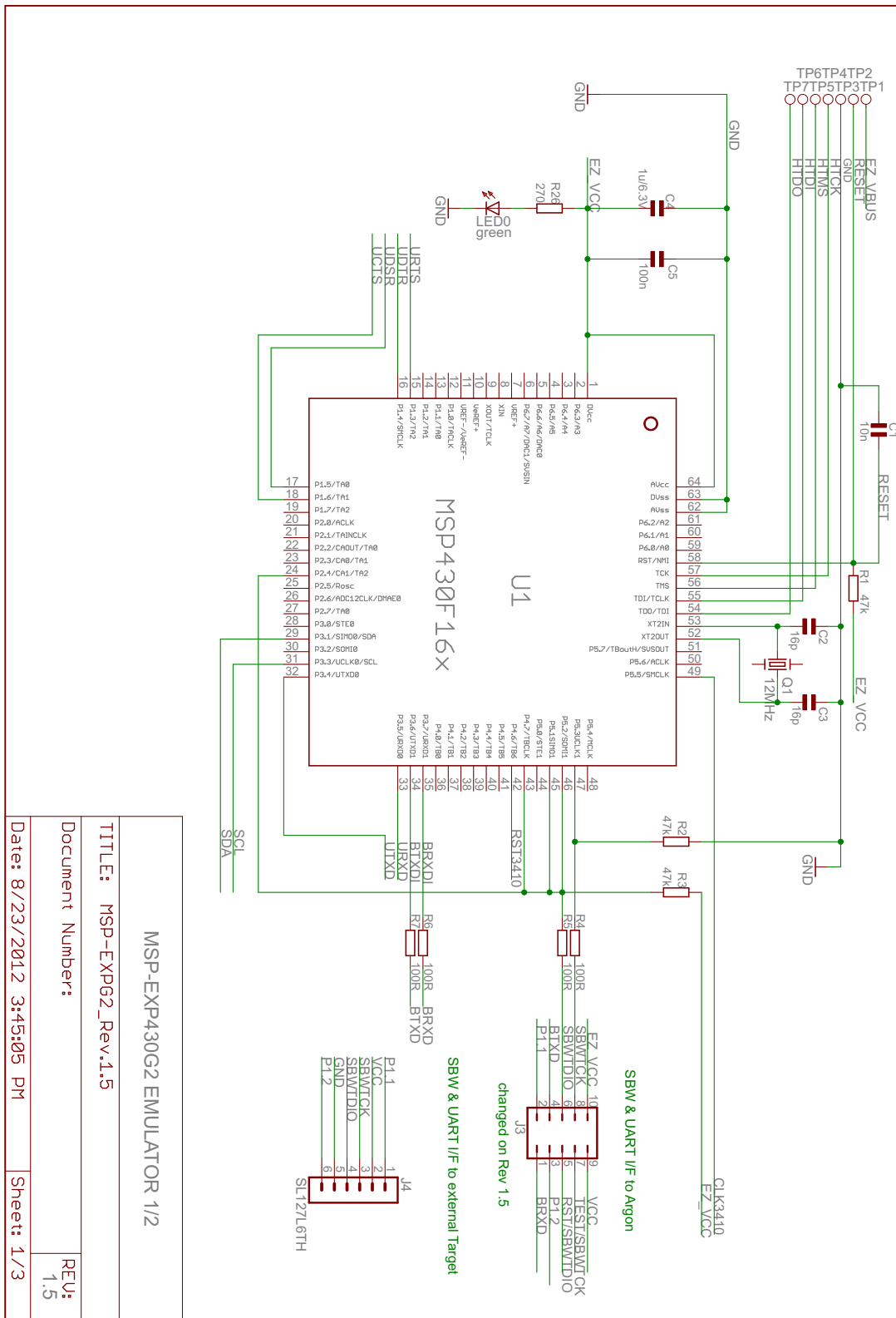


Figure 9. Schematics, MSP-EXP430G2 Emulator (1 of 2), Revision 1.5

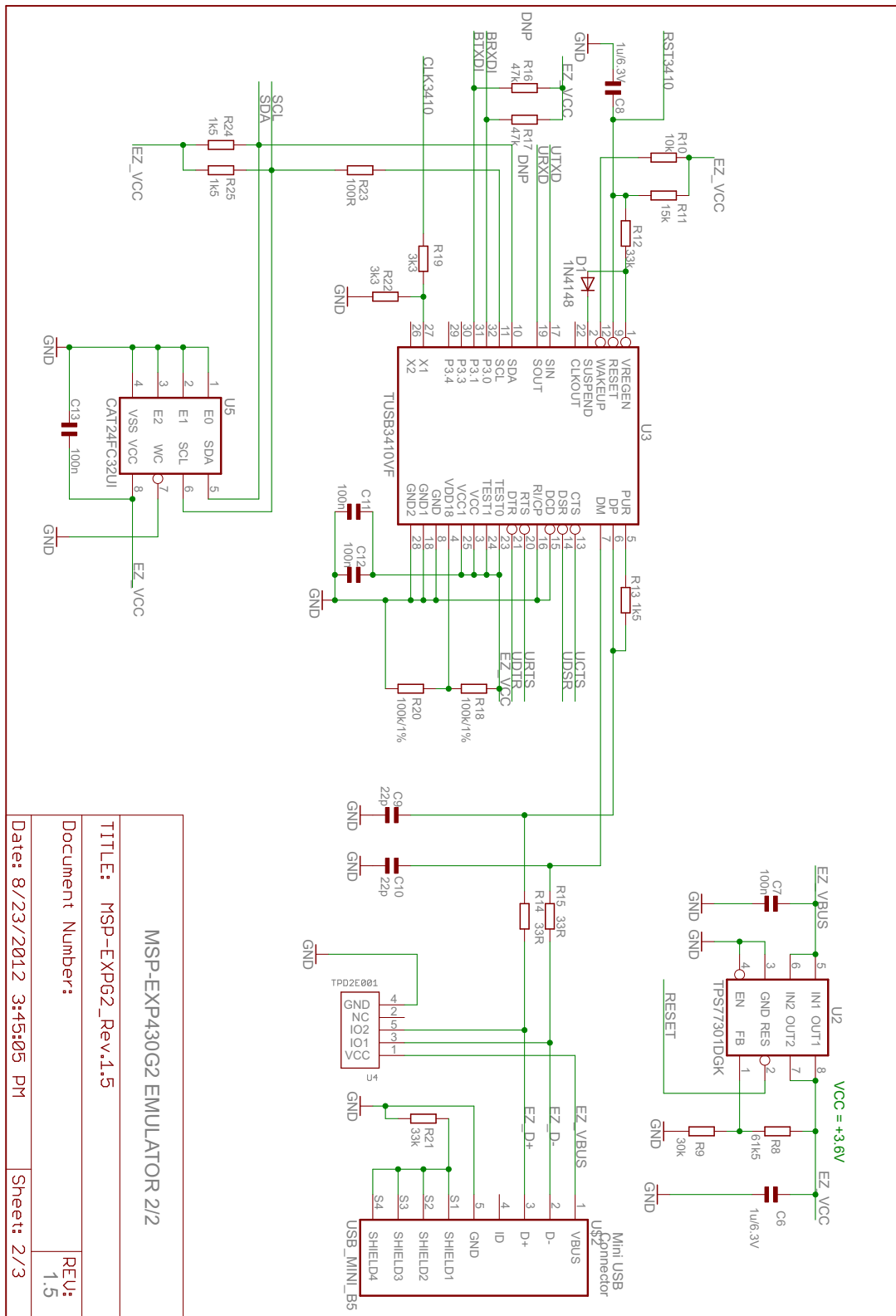


Figure 10. Schematics, MSP-EXP430G2 Emulator (2 of 2), Revision 1.5

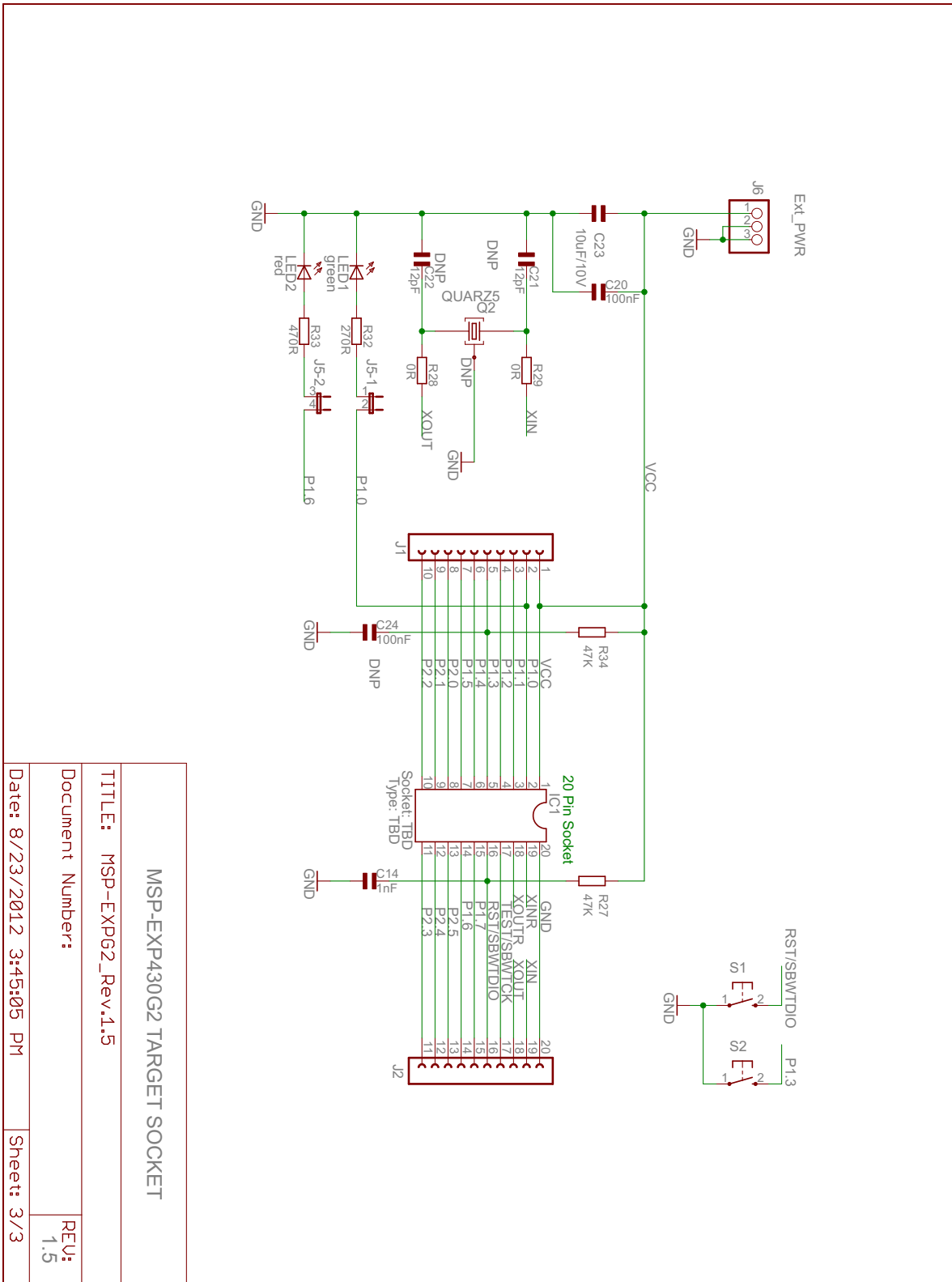


Figure 11. Schematics, MSP-EXP430G2 Target Socket, Revision 1.5

### 5.3 PCB Layout

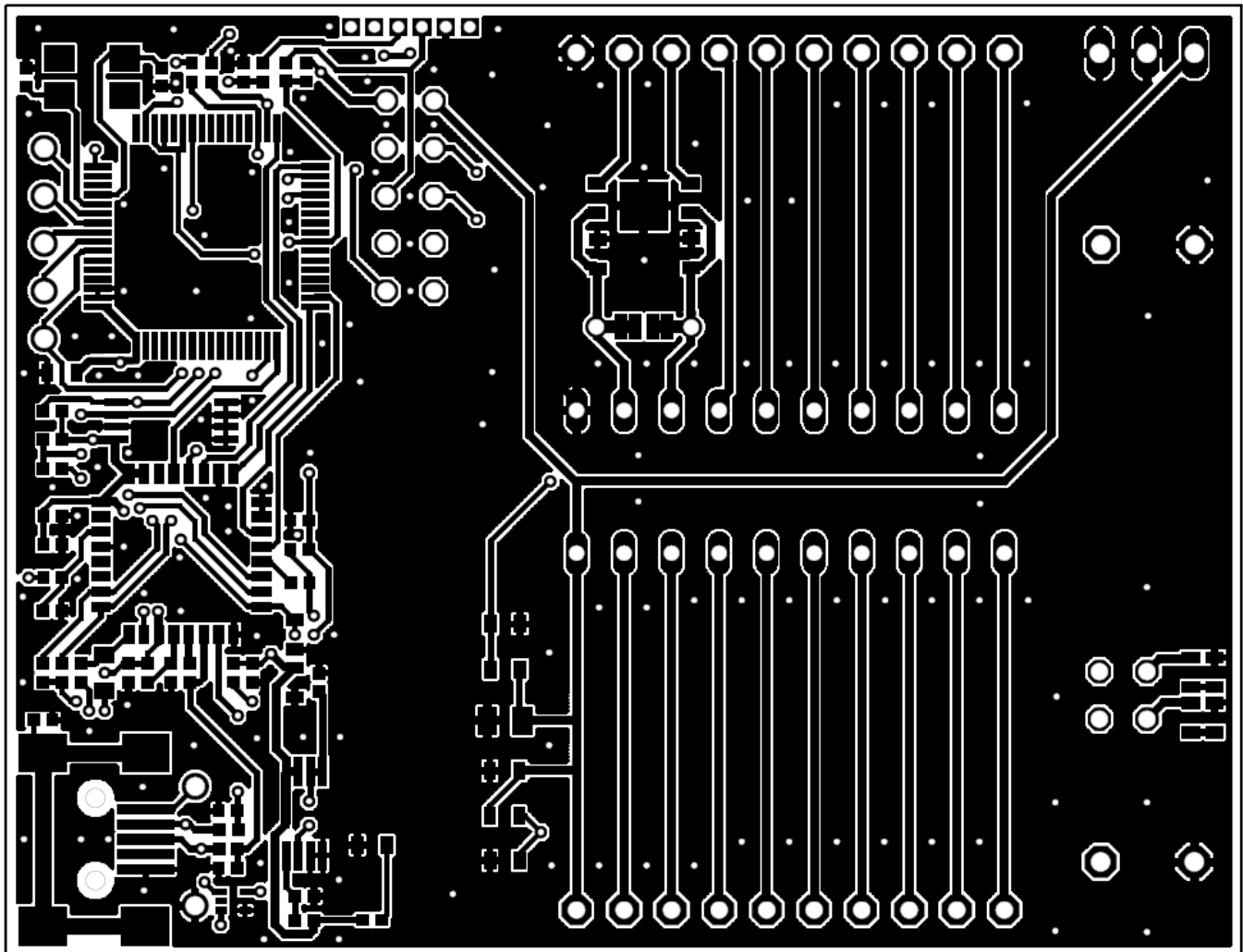


Figure 12. Layout, LaunchPad Top Layer

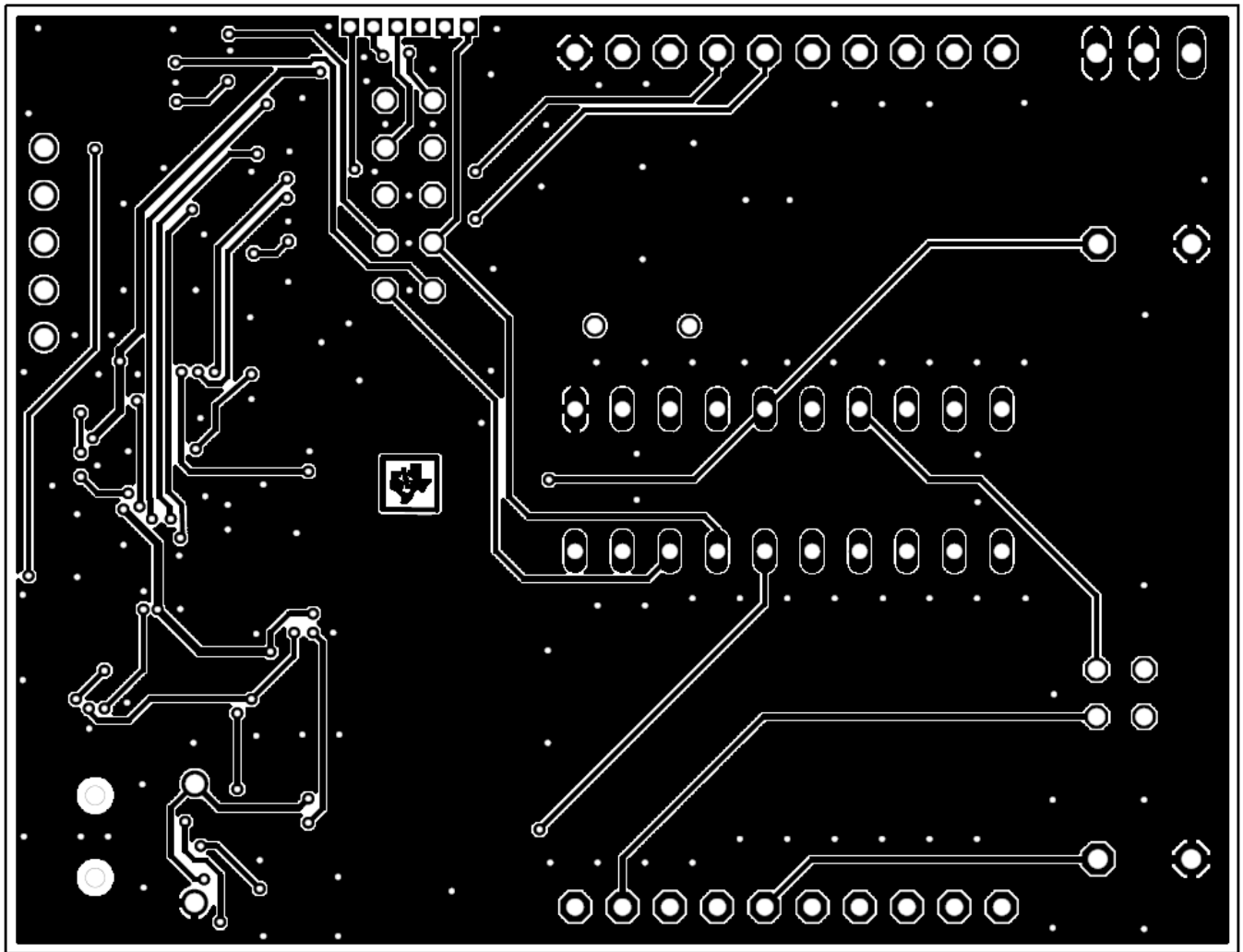


Figure 13. Layout, LaunchPad Bottom Layer

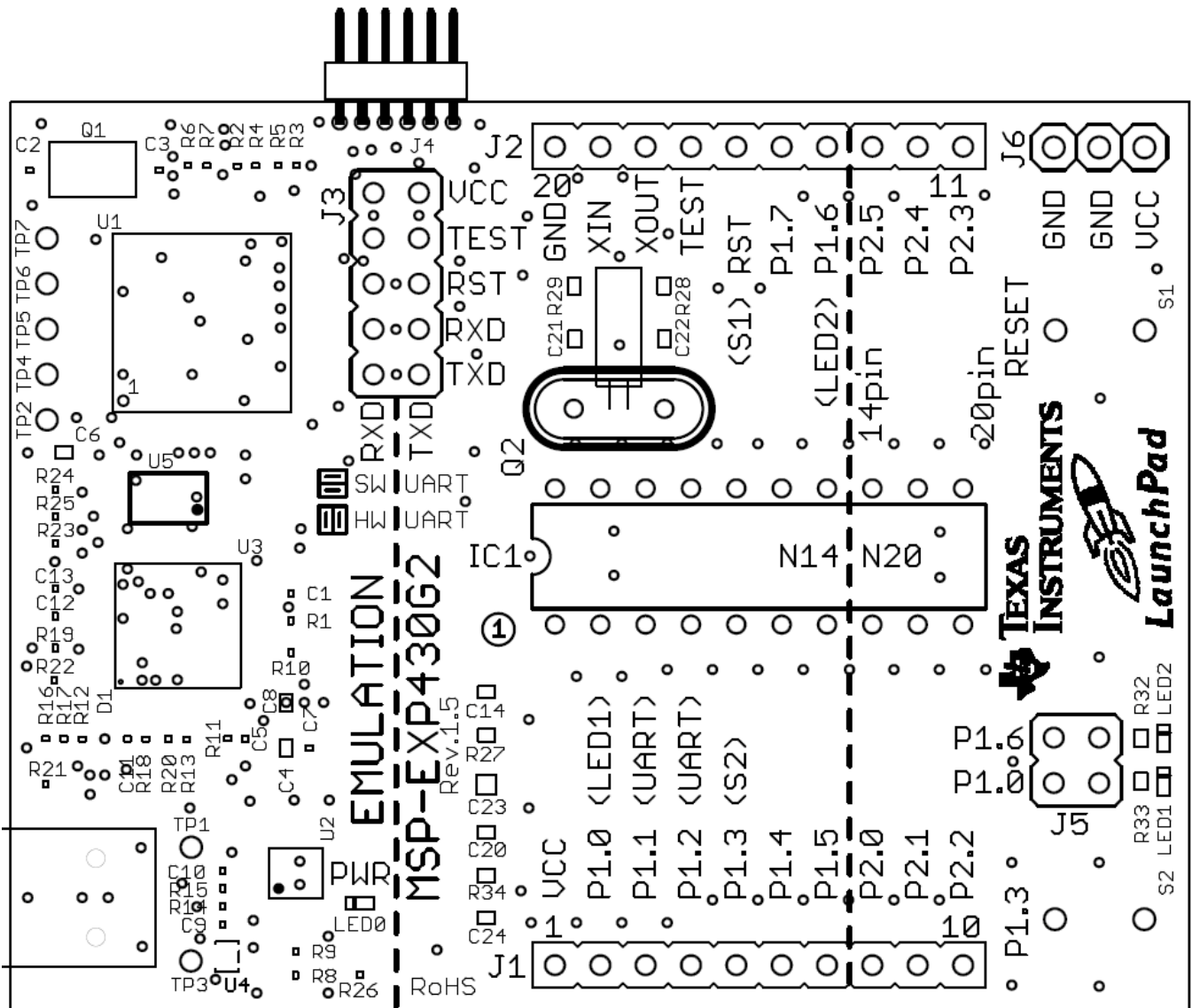


Figure 14. Layout, LaunchPad Silkscreen

## 5.4 Bill of Materials (BOM)

**Table 5. Bill of Materials**

Pos.	Ref Name	Number per Board	Description
1	C2, C3	2	16pF 0402 (33 pF on Rev 1.3)
2	C9, C10	2	22pF 0402
3	C1	1	10nF 0402
4	C5, C7, C11, C12, C13	5	100nF 0402
5	C4, C6, C8	3	1 $\mu$ F, 6.3V 0604
6	D1	1	1N4148 MicroMELF
7	EZ_USB	1	Mini-USB connector
8	Q1	1	SMD oscillator 12 MHz
9	R1, R2, R3, R16, R17	3	47k 0402 (R16, R17 is not populated)
10	R8	1	61k5 0402 (6k8 in Rev 1.3 and prior)
11	R19, R22	2	3k3 0402
12	R9	1	30k 0402 (3k3 in Rev 1.3 and prior)
13	R12, R21	2	33k 0402
14	R4, R5, R6, R7, R23	5	100R 0402
15	R14, R15	2	33R 0402
16	R18, R20	2	100k 0402
17	R13, R24, R25	3	1k5 0402
18	R10	1	10k 0402
19	R11	1	15k 0402
20	U1	1	MSP430F1612IPMR
21	U4	1	TPD2E001DRLR
22	U3	1	TUSB3410VF
23	U2	1	TPS77301DGKR
24	U5	1	I2C EEPROM 128k (AT24C128-10TU-2.7)
25	TP1, TP2, TP3, TP4, TP5, TP6, TP7		
26	C14	1	1nF, SMD 0603
27	C21, C22		12.5pF, SMD 0603 (not populated)
28	C23	1	10 $\mu$ F, 10 V, SMD 0805
29	C20, C24	1	100nF, SMD 0603 (C24 is not populated)
30	LED0, LED1	2	Green DIODE 0603
31	LED2	1	Red DIODE 0603
32	R34, R27	1	47k SMD 0603 (R34 is not populated)
33	R32, R26	2	270R SMD 0603
34	R33	1	470R SMD 0603
35	R28, R29	2	0R SMD 0603
36	IC1	1	DIP20 socket
37	Q2		Clock crystal 32kHz (Micro Crystal MS3V-T1R 32.768kHz CL:12.5pF $\pm$ 20ppm included)
38	J1, J2,	2	10-pin header, TH, 2.54mm male (female header included)
39	J3	1	2X05 pin header male
40	J4		6 pin header male 1.28mm
41	J5	1	2x02 pin header male
42	J6	2	3-pin header, male, TH
43	S1, S2	2	Push button

## 6 Suggested Reading

The primary sources of MSP430™ information are the device-specific data sheets and the family user's guides. The most up-to-date versions of those documents can be found at the Texas Instruments [MSP430 landing page](#).

For more information on CCS and IAR, download the latest version from <http://www.ti.com/mspds> and read the included user's guides and documentation in the installation folder. Documents describing the IAR tools (Workbench/C-SPY, the assembler, the C compiler, the linker, and the library) are located in common\doc and 430\doc. All necessary CCS documents can be found in the msp430\doc folder in the CCS installation path. The FET user's guide also includes detailed information on how to set up a project for the MSP430 using IAR or CCS, and it is included in most of the IDE releases and on the TI MSP430 side.

## 7 Frequently Asked Questions (FAQ)

1. Can other programming tools like the MSP-FET430UIF interface the MSP-EXP430G2 LaunchPad socket device?

The LaunchPad evaluation kit works with any programming tool that supports the 2-wire Spy-Bi-Wire interface. Both the MSP430 USB FET (MSP-FET430UIF) and the Gang Programmer (MSP-GANG430) support these devices, but the connection must be made directly to the dedicated Spy-Bi-Wire ports. See *MSP-FET430 Flash Emulation Tool User's Guide* ([SLAU138](#)) for details on using MSP430 USB FET and the Gang Programmer for a 2-wire Spy-Bi-Wire interface. Do not try to connect the standard JTAG connector to the MSP-EXP430G2 pinheads, as this could result in damage to the attached hardware.

2. Does the MSP-EXP430G2 support fuse blow?

The MSP-EXP430G2 LaunchPad evaluation kit onboard debugging interface lacks the JTAG security fuse-blow capability. To ensure firmware security on devices going to production, the USB Flash Emulation Tool or the Gang Production Programmer, which support the fuse-blow feature, are recommended.

3. What versions of IAR Embedded Workbench and Code Composer Studio are supported?

The MSP-EXP430G2 LaunchPad hardware is supported by IAR Embedded Workbench KickStart Version 6.00 or higher and Code Composer Studio v4 or higher. To download the IDE visit <http://www.ti.com/mspds>.

4. What are the part numbers for the connectors between the LaunchPad emulator board and the other eZ430 target boards?

Header: MALE CONN HEADER .050" 6POS PCB R/A (for example, Digi-Key: S9016E-06-ND)

Socket: FEMALE CONN HEADER .050" 6POS PCB R/A (for example, Digi-Key: S9010E-06-ND)

5. I am not able to select the MSP430 Application UART and cannot receive data.

Ensure that the Application UART driver is correctly installed. This is done by installing either IAR Embedded Workbench or Code Composer Studio v4.

To determine if the driver is correctly installed:

- a. Plug in the MSP-EXP430G2 LaunchPad with the included Mini USB cable.
- b. Right click My Computer and select Properties.
- c. Select the Hardware tab and click on Device Manager.
- d. Under Ports (COM & LPT) should be an entry for "MSP430 Application UART (COM xx)".

If the entry is there, but no characters are received, reconnect the LaunchPad to the PC and restart the application to reload the drivers. If the Application UART is not listed, install the driver by following the instructions in [Section 2.2](#).

If the application UART is installed but not receiving UART data, ensure that the jumpers on J3 are configured for the proper UART communication. The two UART jumpers are configured vertically for a software (SW) UART, and horizontally for a hardware (HW) UART. The application implementation and J3 jumpers should match for UART data to be properly transmitted.



6. The device is not answering to any communication, JTAG or UART.

If you are experiencing difficulties in communicating to the attached MSP430 target device, even though all the communication drivers for the MSP-EXP430G2 are loaded correctly, the emulator is probably set to a wrong communication state. This can be fixed by reconnecting the LaunchPad evaluation kit and restarting the communicating application. Also make sure that all the jumpers on J3 are connected properly between the emulator and the target device. On revision 1.5 and newer, the orientation of the UART jumpers must align with the software implementation on the target device.

7. I soldered the 32-kHz crystal to the board and the oscillation is not starting.

The MSP430 driving capabilities for the low-frequency crystal is limited, because it is designed for low-power applications. To ensure proper operation, the load on these pins must be as small as possible, the matching capacitors (12.5 pF for 32.768 kHz) for the crystal must be soldered to the board, and the resistors R28 and R29 must be removed. Measuring the frequency of the oscillation with an oscilloscope typically disturbs the oscillation.

8. The power consumption of the board is much higher than specified in the device data sheet, or I am not measuring a current at all.

The MSP430 device inside of the LaunchPad socket can be powered with an external power supply at header J6 or J4. To measure the power consumption in this mode, the VCC jumper, usually used to measure the power consumption, must be removed, and the current must be measured directly at the power supply. If the jumper J3 is not removed, the emulator circuitry of the LaunchPad is powered as well. Measuring the current consumption during a debug session is not possible, because the cross current through the JTAG connection influences the measurement. The most accurate results are achieved with all jumpers on J3 removed. If the measurement is still not matching the data sheet parameters, make sure that the code is aligned with all the power saving recommendations on the web site [MSP430™ - The World's Lowest Power MCU](#).

LaunchPad revisions 1.3 and 1.4 come with R34 populated. The 47-kΩ resistor is used as a pullup for the button S2. If the port P1.3 is driven to ground, as suggested to keep the power consumption down, the pullup resistor generates an additional current of approximately 77 μA. To reduce the power consumption, the port should stay in input mode or the resistor should be removed if button S2 is not used. The internal pullup of the MSP430G2xx can be used instead.

## Revision History

<b>Changes from D Revision (April 2013) to E Revision</b>	<b>Page</b>
• Changed link to TI E2E Forum .....	4
• Removed section titled "FCC Warning"–refer to "REGULATORY COMPLIANCE INFORMATION" at end of document ..	4
• Changed all occurrences of "experimenters board" to "evaluation kit" throughout document .....	4
• Changed <a href="#">Section 1.1</a> .....	4
• Changed bullet that starts "Rearranged jumper J3..." .....	6
• Changed link to software download .....	6
• Added GUI source information and link to Processing web site .....	7
• Removed obsolete references to wiki .....	7
• Changed link to demo source code .....	8
• Replaced all contents of <a href="#">Section 4.6</a> .....	11
• Changed all occurrences of "touch sense" to "capacitive touch" throughout document (TouchSense is a trademark of Immersion Corporation) .....	11
• Changed link to latest versions of documents .....	24
• Changed links to CCS and IAR .....	24
• Corrected LaunchPad name .....	24
• Changed link to download the IDE .....	24
• Added paragraph that starts "If the application UART is installed..." .....	24

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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### For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

#### Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

### FCC Interference Statement for Class A EVM devices

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### **FCC Interference Statement for Class B EVM devices**

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

### **For EVMs annotated as IC – INDUSTRY CANADA Compliant**

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

### **Concerning EVMs including radio transmitters**

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

### **Concerning EVMs including detachable antennas**

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

### **Concernant les EVMs avec appareils radio**

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

### **Concernant les EVMs avec antennes détachables**

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

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**This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan**

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

1. Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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2. You have full and exclusive responsibility to assure the safety and compliance of your products with all such laws and other applicable regulatory requirements, and also to assure the safety of any activities to be conducted by you and/or your employees, affiliates, contractors or designees, using the EVM. Further, you are responsible to assure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard.
3. Since the EVM is not a completed product, it may not meet all applicable regulatory and safety compliance standards (such as UL, CSA, VDE, CE, RoHS and WEEE) which may normally be associated with similar items. You assume full responsibility to determine and/or assure compliance with any such standards and related certifications as may be applicable. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

**Certain Instructions.** It is important to operate this EVM within TI's recommended specifications and environmental considerations per the user guidelines. Exceeding the specified EVM ratings (including but not limited to input and output voltage, current, power, and environmental ranges) may cause property damage, personal injury or death. If there are questions concerning these ratings please contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, some circuit components may have case temperatures greater than 60°C as long as the input and output are maintained at a normal ambient operating temperature. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors which can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during normal operation, please be aware that these devices may be very warm to the touch. As with all electronic evaluation tools, only qualified personnel knowledgeable in electronic measurement and diagnostics normally found in development environments should use these EVMs.

**Agreement to Defend, Indemnify and Hold Harmless.** You agree to defend, indemnify and hold TI, its licensors and their representatives harmless from and against any and all claims, damages, losses, expenses, costs and liabilities (collectively, "Claims") arising out of or in connection with any use of the EVM that is not in accordance with the terms of the agreement. This obligation shall apply whether Claims arise under law of tort or contract or any other legal theory, and even if the EVM fails to perform as described or expected.

**Safety-Critical or Life-Critical Applications.** If you intend to evaluate the components for possible use in safety critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, such as devices which are classified as FDA Class III or similar classification, then you must specifically notify TI of such intent and enter into a separate Assurance and Indemnity Agreement.

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